

Efficiency  
**>87%**

Remote  
**ON OFF**

Full Metal  
**Package**

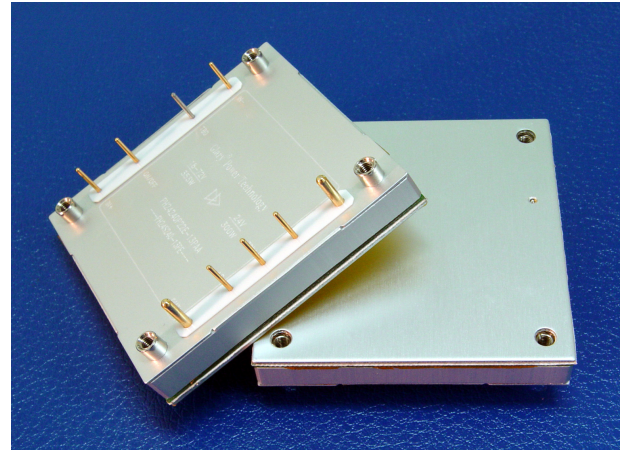
0.38"  
**Ultra-Low  
Profile**

2.23Mhrs  
**MTBF**

**OCP**

**OTP**

**OVP**



Demo photo only. Actual outlook & marking may vary.

**EXAMPLE OF DESCRIPTION:** **IAH1H240P20E-06xx0** is an Immense Amazon series Half brick of 65~160Vin / 24Vout / 6Amp with Positive logic in a metal enclosure package of 0.2" pin length and 0.02" stand-off height with 4 x M3 screw stands through the unit, featuring ultra-low profile of 0.38" total module height, where the end codes  
 "xx" = Purchase code assigned by manufacturer for commercial purpose only, and  
 "0" = Product version 0 with Glary Power standard settings and features.

#### MODEL NUMBER SYSTEM

IAH	1H	240	P	2	0	E	-	06	xx	0
Series Name	Input Voltage	Output Voltage (0.1V Increments)	Enable Logic	Pin Dimension	Standoff Height	Base-Plate/Module Thickness		Output Current	Suffix	Version
Immense Amazon series Half brick	1H= 65~160Vdc	240= 24Vdc	P: Positive N: Negative	0 : 0.12" 1 : 0.16" 2 : 0.20" 3 : 0.24"	0 : 0.02" 1 : 0.08" 2 : 0.16"	E : Metallic enclosure/0.36"	-	00~21 : For output current rating		For marketing purpose only

\*\*\* Total Module Height = Module thickness + Standoff height.

#### EXISTING IAH1H MODELS (Contact to factory for special input / output)

Model Number	Maximum Input	Maximum Output	Efficiency
IAH1H120xxxE-13xx0	65~160V 180W	12V/13A 156W	87%
IAH1H240xxxE-06xx0	65~160V 160W	24V/6A 144W	90%
IAH1H240xxxE-13xx0	65~160V 346W	24V/13A 312W	90%
IAH1H480xxxE-03xxY	175~255V 133W	48V/2.5A 120W	90%

#### REFERENCED THERMAL IMAGES

Not applicable for enclosure models.

## GENERAL SPECIFICATIONS

Absolute Maximum Ratings		
Temperature	Operation Storage	-40°C to +110°C -55°C to +125°C
Input Voltage Range	Operation: 110V Models  Transient (100mS): 110V Models	65V to +260Vdc  200V Maximum
Isolation Voltage	Input to Output Input to Case Output to Case	2.0KV Minimum 1.0KV Minimum 1.0KV Minimum
Remote Control		-0.5V to +12Vdc

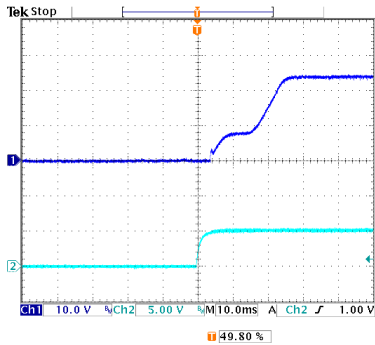
General Parameters		
Conversion Efficiency	Typical	See table
Switching Frequency	Typical	360KHz
MTBF	Bellcore TR-332 issue 6	2.23×10 <sup>6</sup> hrs @GB/25°C.
OTP	Internal	110°C(Tc) ±5°C
Weight	Metallic enclosure	119g

Control Functions		
Remote Control	Logic High Logic Low	+3.0V to +6.5V 0V to +1.0V
Input Current of Remote Control Pin		-0.5mA ~ +1.5mA

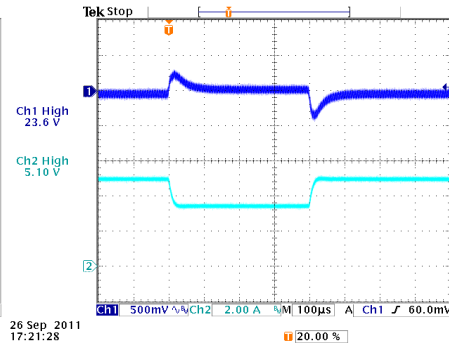
Input		
Operation Voltage Range	110V Models	+65V to +160Vdc
Reflected Ripple Current	L <sub>EXT</sub> = 10uH	30mA rms/100mAp-p
Power ON Voltage Ranges	110V Models	+61.4V to +65.0Vdc
Power OFF Voltage Ranges	110V Models	+56.2V to +59.8Vdc
Off State Input Current	V <sub>NOM</sub>	6mA Max
Latch-State Input Current	V <sub>NOM</sub>	8mA Max
Input Capacitance	110V Models	3.3uF Max

Output		
Voltage Accuracy	Typical	±1.0%
Line Regulation	Full Input Range	±0.2%
Load Regulation	2%~100%	±0.2%
Temperature Drift	-40°C ~100°C	±0.03%/°C
Output Tolerance Band	All Conditions	±4%
Ripple & Noise (20MHz)	Peak-Peak (RMS)	3% (1%) V <sub>O</sub>
Over Voltage Protection	V <sub>NOM</sub> , 10% Load	115~130 %V <sub>O</sub>
Output Current Limits	V <sub>NOM</sub>	108%~125%
Voltage Trim	V <sub>NOM</sub> , 10% Load	±10%
Input Ripple Rejection (<1KHz)	V <sub>NOM</sub> , Full Load	-50dB
Step Load (2.5A/μS)	50%~75% Load	640mV/500μS
Start-Up Delay Time	V <sub>NOM</sub> , Full Load	30mS/250mS

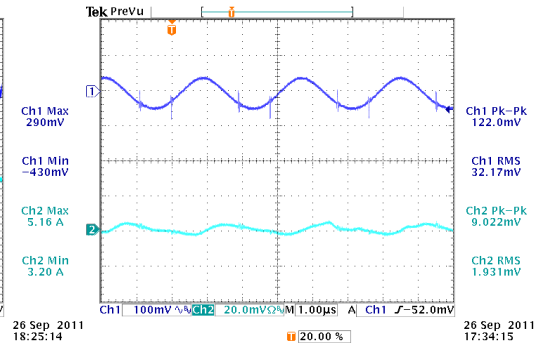
### TYPICAL WAVES AND CURVES (Below waveforms are of instantly available IAH1H240P20E-06xx0 model for typical reference.)



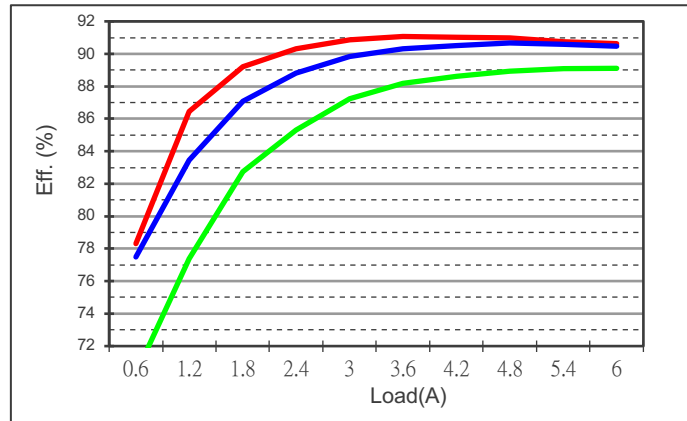
Start-Up Waveform  
(V<sub>IN</sub>: 110V, Load: 6A)



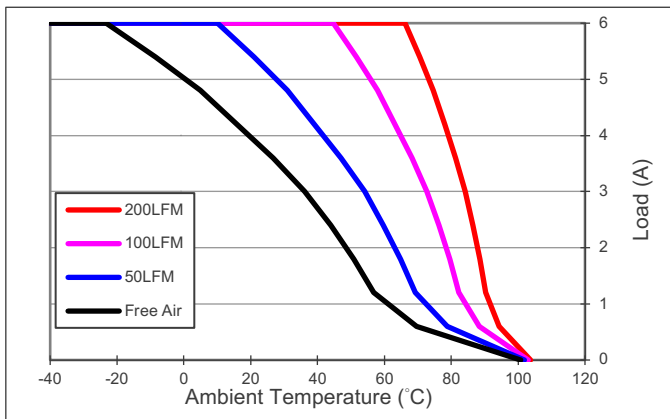
Transient Response  
(V<sub>IN</sub>: 110V, Load: 4.5A/3A@2.5A/μs)



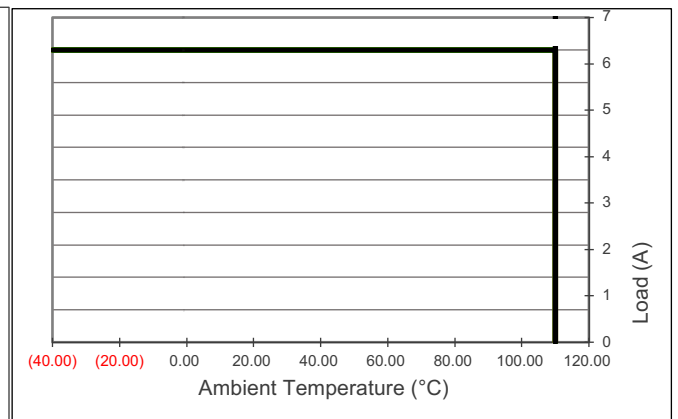
Output Ripple/Noise and Input Ripple Current  
(V<sub>IN</sub>: 110V, Load: 6A, L<sub>IN</sub>=20μH, C<sub>IN</sub>=270μF)



Efficiency plot of IAH1H240P20E-06xx0



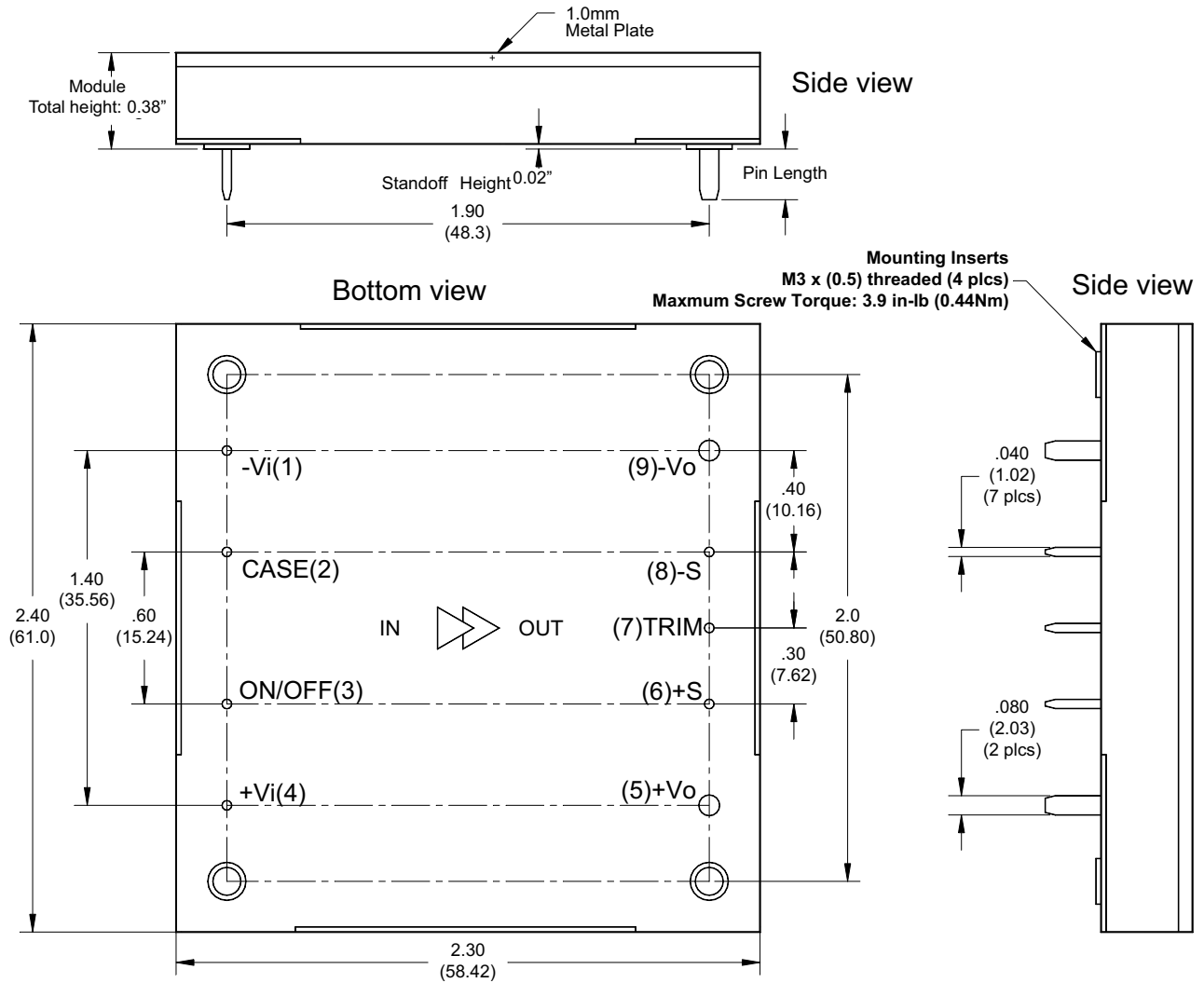
Calculated de-rating curves of IAH1H240P20E-06xx0 along with no extra heat-sink for max. T<sub>C</sub>= 105°C



Calculated de-rating curves of IAH1H240P20E-06xx0 being attaching to system cold wall for max. T<sub>C</sub>= 110°C

**IMPORTANT NOTE:** Due to natural interaction between various tolerances of the components used in this product, de-rating performance of different units of the same model can be similar but not exactly the same. A higher OTP set point may also result in de-rating curves that "appear" to be much better. However, the key should always be whether or not the other devices in customer system are able to survive in a constant high temperature environment. The de-rating curves, calculated or actual measured, are therefore used as a reference only and it is strongly recommended for the actual usage to run the units under the curves' limits in real application. **Due to the very high power density, in the majority of the actual applications, attaching the unit to the system cold wall would usually be highly recommended, while adding extra forced air would surely be better.**

### METAL ENCLOSED PACKAGE



### Dimensions and Pin Connections

Designation	Function Description	Pin #
-Vi	Negative input	1
CASE	Connected to base plate	2
ON/OFF	Remote control. To turn-on and turn-off output.	3
+Vi	Positive input	4
+Vo	Positive output	5
+S	Positive remote sense	6
TRIM	Output voltage adjust	7
-S	Negative remote sense	8
-Vo	Negative output	9

**Dimensions:** inches (mm)

**Tolerances:** .xx±0.02 (.x±0.5)  
.xxx±0.01 (.x±0.25)

**Weight:** 95g / 1.0mm metal plate

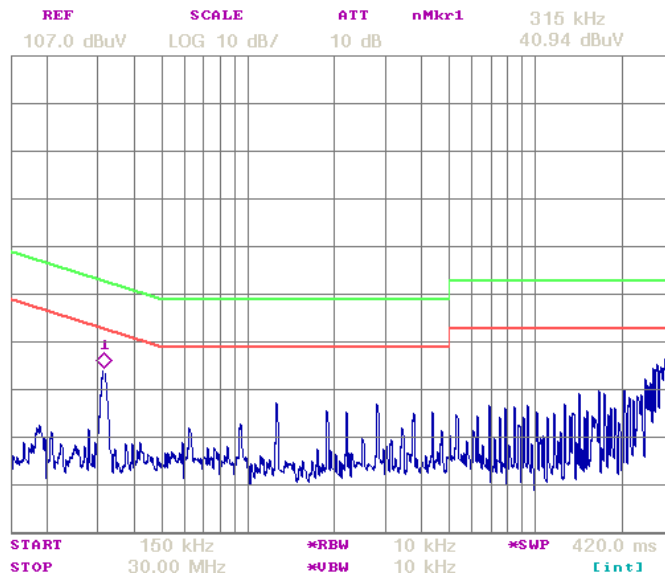
**Base plate:** Aluminum alloy with anode oxide

**Mounting inserts:** Stainless steel  
**Maximum torque:** 3.9 in-lb (0.44Nm)

**Pin material:** Copper alloy or Brass

**Pin plating:** Golden over Nickel

#### REFERENCED EMC CIRCUIT

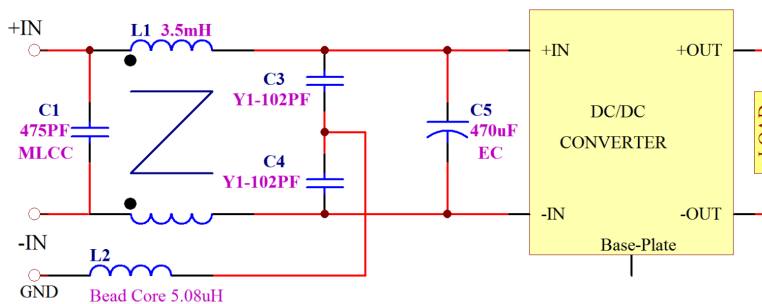


#### Referenced EMC Performance

The tested result shown in left-hand side is obtained by loading the power module with a resistive load only. It can be used as a design reference for customer system. However! The performance of customer's system depends on the whole system design. It should be noted that modifications on the circuit parameters and fine adjustment of the final layout affect the final EMC performance greatly.

#### Bandwidth of EMC Components

No components are ideal for infinite frequency range. The bandwidth of EMC components should be taking into consideration when designing an EMC filter circuit. To connect ceramic capacitor with electricity capacitor in parallel and connect low inductance inductor with big one could get a better bandwidth.



Measured conductive level of IAH48280abcd-11XXX and referenced filter circuit

#### NOTE:

1. It is recommended that the input should be protected by fuses or other protection devices.
2. All specifications are typical at nominal input, full load and 25°C unless otherwise noted.
3. Specifications & product outlook are subject to change without notice.
4. Printed or downloaded datasheets are not subject to Glary document control.
5. Product labels shown, including safety agency certificates, may vary based on the date of manufacture.
6. Information provided in this documentation is for ordering purposes only.
7. This product is not designed for use in critical life support systems, equipment used in hazardous environments, nuclear control systems or other such applications, which necessitate specific safety and regulatory standards other than the ones listed in this datasheet.

#### IMPORTANT

- ✳ General specifications and the performances are related to standard series only, no special customer specification display here except requested items.
- ✳ In order to secure effective usage of converter and the validity of Glary's service and warranty coverage, please refer to the application notes for general usage. For needs of usage beyond the application notes, please contact to Glary headquarter or our regional sales representative office for help.

## General Operating Information

### General

#### Absolute Maximum Ratings

Some ratings, shown in ABSOLUTE MAXIMUM RATINGS, are the absolute maximum ratings referring to no destruction or design limits, normally tested with each indicated single parameter by exceeding the limits of its absolute maximum ratings or electrical characteristics. The stress exceeding the absolute maximum ratings may cause permanent damage, function and performance degraded to the converter.

The over temperature protection set point is 5°C ~10°C higher of maximum operation base plate temperature, which can be as high as 130°C for some special product series. As far as design margin and enhancing system reliability are concerned, it is recommended that Glary DC/DC converters operate below 90°C of case temperature.

### Safety

#### Standards

All product series of Glary DC/DC converters, with or without official certificates, are designed to comply with UL in accordance with EN60950 safety of information technology equipment including electrical business equipment. These DC/DC converters meet the U.S. and Canadian Standard for safety of information technology equipment, including electrical business equipment applicable requirement in CSA/UL60950. Most product series of Glary DC/DC converters are recognized by UL, CSA and TUV.

#### Isolation

Operational or Basic insulation is performed in accordance with EN60950. All product series, built in DC-to-DC converter power supplies, should be installed in end-use equipment for printed wiring board or chassis mountable, and intend to be supplied by

isolated secondary circuit. Consideration should be given to measure the case temperature and ensure that it does not exceed the maximum case temperature during module operation.

When the supply to DC/DC converter meets all requirements for SELV, the output is considered to remain SELV limit. For supply voltage from 60V to 75V DC, reinforced insulation must be provided in the 75V power source that isolates the input from the mains. Single fault testing in the 75V supply circuit shall be performed in combining with the DC/DC converter to demonstrate that the output meets the requirement for SELV. One pole of the input and the other one of the output shall be grounded or both circuits are to be kept floated.

The isolation, withstanding 1500V or 2000 DC between input and output depending on different series, 1000V DC between input/output and case with all series, is verified in an electrical strength test.

#### Flammability

The flammability ratings of plastic parts and PCBs meet UL-94V-0.

#### Fusing

A fuse should be used at the input of each converter to isolate the failed one from others, keeping the system continue to operate and prevent the damage of power distribution wiring from over heating. A slow blow fuse should be used with 10A~20A rating or less, it is recommended using a fuse with the lowest current rating.

### Input Side

#### Input (+IN, -IN)

#### Voltage Range

The input voltage range of 36V~75V meets the requirement of European Telecom Standard ETS 300

132-2 for normal input voltage range in -48V (-40.5V~ -57.0V) and -60V (-50.0V~ -72.0V) DC power systems. The absolute maximum continuous input voltage is 75V DC and withstands 100V DC/100ms maximum transient voltage. The range 18V~36V for 24V version is also available.

### Input Capacitance

The input characteristic of a DC/DC converter may be referred as a negative-incremental impedance element in its input voltage range. Sometimes, oscillation will be occurred when high impedance power source is applied to supply power to a DC/DC converter. An external input capacitor is recommended to reduce the characteristic impedance and eliminate the oscillation between the DC/DC converter and the source.

### ON/OFF Control (ON/OFF or PC)

These product series of DC/DC converter has the remote on/off control pin that can be connected to an external ON/OFF control signal for turning ON and OFF the converter. The control signal of ON/OFF pin is referred to the negative power input pin and two control logic options are available.

#### Negative Logic

**ON:** Short to negative power input pin or apply voltage of logic low.

**OFF:** Opening circuit or apply the voltage of logic high.

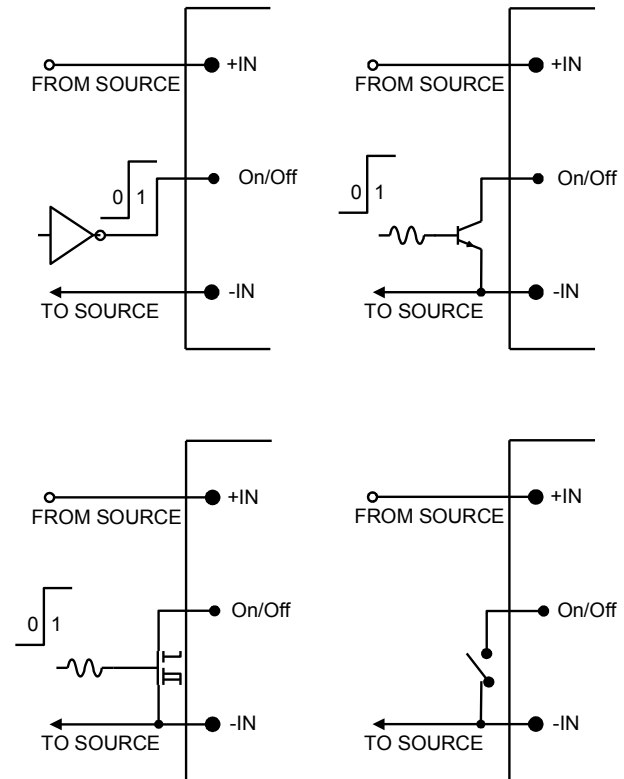
#### Positive Logic

**ON:** Opening circuit or apply the voltage of logic high.

**OFF:** Short to negative power input pin or apply voltage of logic low.

A mechanical switch or an open collector NPN transistor (open drain N channel FET) can be used to drive the ON/OFF pin. The device must be capable of

sinking 1mA minimum at a logic low voltage 1.0V and withstands 12V DC minimum. Additional external component such as diodes or resistors for connecting the ON/OFF pin in series are not recommended.



### Output Side

#### Output (+OUT, -OUT)

#### Ripple & Noise

The ripple of DC/DC converters is measured as peak-to-peak voltage from 0 to 20MHz including the noise and the fundamental ripple. The ripple and noise can be reduced significantly by paralleling a decoupling capacitor to the output terminal.

#### Over Current Protection (OCP)

These DC/DC converters provide OCP function to withstand continuous overload or short circuit condition in the output. The converter will recover to normal operation after the overload is removed. The OCP set point of these DC/DC converters is 108%~125% of rated output current.



## Output Over Voltage Protection (OVP)

These DC/DC converters provide OVP function to prevent the damage of load from over voltage condition on the output. The converter will restart after recycling the input power or control signal of primary control pin. The OVP set point of these DC/DC converters is 115%~130% of rated output voltage.

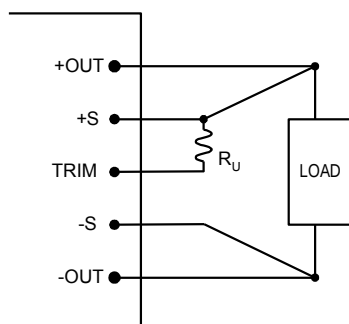
## Remote Sense (+S, -S)

These DC/DC converters have the remote sense pins that can be used to compensate voltage drop due to the resistance in the distribution system. It allows the output voltage can be regulated at the load or a selected point. It should be noted that the sense line must be located close to a ground trace or a ground panel to reduce noise, a twisted wire pair is recommended for discrete wiring. The sense pin will compensate 0.5V maximum of voltage drop between the sensed voltage and the voltage of output pins.

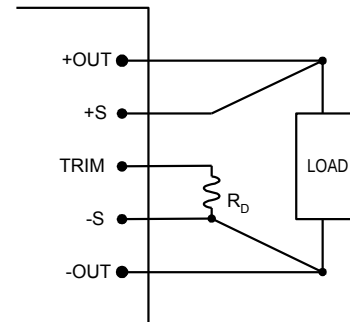
## Output Voltage Adjust (TRIM or SC)

These DC/DC converters have the secondary control pin used to adjust output voltage beyond or below nominal output voltage. It should be noted that trim up to be above OVP set point may cause a converter to enter the over voltage protection state. The TRIM pin is noise sensitivity and the external resistors should be located within 1cm of the converter. If not using the trim feature, leave the TRIM pin open.

**TRIM UP:** connect a trim resistor ( $R_U$ ) between TRIM pin and +S pin.



**TRIM DOWN:** connect a trim resistor ( $R_D$ ) between SC pin and -S pin.



## Output Capacitance

The extra output capacitance is required to improve the voltage regulation when powering a load with significant dynamic current requirement. Putting a low ESR capacitor to the load as close as possible to handle the short duration high frequency component of dynamic load current and put the higher value of electrolytic capacitor to progress the mid-frequency component. The stray capacitance, resistance and inductance of distribution system are used as feedback components that would in affecting stability and dynamic response performance of power converter.

In generally, 47uF~68uF/A of output current can be used for 3.3V output power module without additional analysis. For example, a 35A DC/DC converter, the de-coupling capacitor up to 4700uF can be used on the premise of not affecting the stability. Capacitor of a higher value, as much capacitance as possible, is however not encouraged as it may result in stability risks to the converters. Since the stored energy of the capacitor is proportional to  $V^2$ , which result in the de-coupling capacitor should be reduced by a factor of  $(V_o/3.3)^2$  for modules with higher output voltage. Some applications may require longer hold-up time to be performed by high output capacitance anyway, and in such case, the capacitors should be placed at



outside of the feedback loop and as close as possible the load, which should help with ensuring the stability. The absolute maximum value of output capacitance is 10,000uF; Yet it is suggested that the user should consult with Glary for high value of output capacitance with or without exceeding the above maximum value.

Moreover, the recent modern technology has been advanced enough to allow low ESR on some specific type of capacitors (such as MLCC), which features very high reliability and nearly eliminates the needs of paralleling numerous life span constrained electrolytic caps at the system end to achieve low ESR, and further allows more simplified external output filter design for the power system. Therefore, unless the user has special technical needs, for Glary Power's full series of product lines, simply adding a MLCC of a few to a few tens of uF close to the load should be sufficient enough. Do note that an exceeded high value of external output capacitance would result in other negative impacts to the converter's feed back loop. Please as well consult with Glary Power if higher external output capacitance is needed for the system design when using the above indicated advanced series.

## **Quality**

### **Reliability**

For example, calculated MTBF in accordance with Bellcore TR-332 issue 6, December 1997 of COE series, is 4,801,570hours (+25°C), 2,015,270hours (+50°C), or 940,807hours (+70°C) to demonstrate the reliability of our products. This represents an average failure rate of 280.265 (+25°C), 486.211 (+50°C) and 1,062.918 (+70°C) failures per million unit hours of operations. The assumptions are full load at +25°C, +50°C and +70°C case temperature under ground benign (GB) environment condition.

### **Warranty**

Glary Power Technology warrants to the original purchaser or the end user that the products conform to its data sheet, and are free from material and workmanship defects for a period of two years since the date of manufacturing, when the product is used within the specified conditions and not processed by any party other than Glary Power.

### **Handling**

Open frame converters can be damaged from poor handling, excessive mechanical shock, or from a static electric discharge. The units should be:

- Carefully handled and not subjected to mechanical stress
- Treated as an ESD sensitive component
- Stored in a static protective container which physically protects the converter
- The converters should not be stored in plastic bags, or stacked on top of one another in any way

### **Limitation of Liability**

Glary Power Technology does not make any warranties, express or imply including any warranty of merchantability or fitness for special purposes such as (but not limited to) use in life support applications, nuclear equipment, and defense systems... e.t.c., where malfunction of product can cause injury to a person's health or life.

## General Module Thermal Considerations

### General

The Glary DC/DC converter product series are designed to operate in a variety of thermal environments; however sufficient cooling should be considered and effectively arranged for reliable operation. Generally speaking, the heat is removed from the module by conduction, convection and radiation to the surrounding, but convection is the most important method for the normal application at sea level. Increased airflow may strongly influence the module thermal performance. Proper cooling can be verified by measuring the temperature of base plate.

The available load current with different ambient air temperature and airflow at nominal input voltage for each model is according to real test done in a wind tunnel. However, the actual derating performance of each module may slightly vary compared with the derating curves given by test performed in the data sheet, the 90% of available current shown in the derating curves is the highest recommended value for reliable system design. The actual system design would in fact strongly affect the derating performance and generally result in three variable factors to affect the module derating performance described as below:

### Conversion Efficiency

The heat is generated by power loss. A board mount power module that converts input power for output to the load always has an efficiency between 0%~100%. The synchronous rectification technology can make power module converting the required power with dramatic efficiency and dissipating fewer power compared with traditional technology. This leads to a lower temperature rise if the module thermal resistance is the same; it means higher efficiency is better for any kind of cooling conditions because the temperature is always lower and the

reliability could also be better secured.

However, most data sheet shows high efficiency with full load condition and not with the real load condition of a practical system. It is better to select a power module that has highest efficiency with specified load condition. This almost leads to a solid answer that to choose a power module rated about 1.2~1.5 times of the required power would be reliable than a power module rated at double of the actual required power or even higher, because large derating always has poor efficiency and more temperature rise. Higher derating always reduces the operation life because the temperature factor has more negative effect on MTBF to further eliminate the positive effect due to the reduced electrical stress.

Rough calculations of different results on Glary COQ module by changing the temperature stress and electrical stress shown as below could be used as a reference example of power module selection in system design stage. At 25°C, a 10% increasing of module case temperature ( $T_c = 90^\circ\text{C}$  to  $T_c = 96.5^\circ\text{C}$ ) will reduce the life to about 75% of its originally designed figure. However, Module derating from 100% to 75% should improve its life by about 2%.

Efficiency change between different modules also has significant effect on the temperature rise to affect the derating performance. This effect can be seen more clearly especially in high temperature operation.

For example, assuming a 200LFM/83°C of airflow is used for cooling and the maximum case temperature (OTP trigger point) of power module was set as 110°C. A COQ48050N11M-10 module with 90.2% efficiency can have a 9.5A output current with 5.16W power loss. If the efficiency is 2% lower (88.2%) at 9.5A output, it may loss 6.35W of power and further cause over temperature to  $T_c = 114^\circ\text{C}$  or the maximum operating temperature should be reduced to  $T_a = 75^\circ\text{C}$ .

## Module Temperature

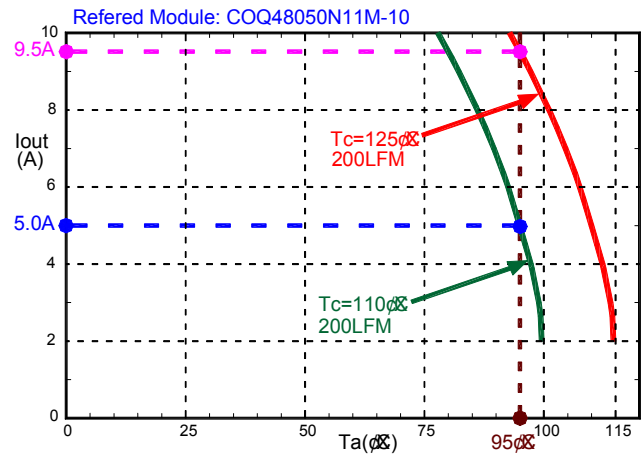
Following the notes of conversion efficiency section; some power module makers provide derating curves by increasing the maximum board temperature and semiconductor junction temperature to 125°C to “show” better derating curves. This method actually pushes the converter to operate in high temperature environment, which results in two effects on the thermal characteristics:

The first effect of increasing maximum allowable temperature is that it would increase the temperature rise between the module and the air, which may cause more heat flow through the module surface to the air, assuming the module thermal resistance is constant (*typically the thermal resistance of a specified form factor is determined by the properties of air and the contacted surface area. The properties of air are fixed when the temperature and pressure were specified. The only variable is the air contacted surface area of the power module, but the same form factor has almost the same construction and the same contacted surface area due to no big difference on the components selection and its counts, so that the thermal resistance can be at the same level*).

The second effect is the increasing of nature convection due to higher temperature rise, and it further results in reduced thermal resistance. It has about 8% improvement for thermal resistance with nature convection by changing the maximum allowable temperature from  $T_c=110^\circ\text{C}$  to  $T_c=125^\circ\text{C}$ .

Simple calculations of a Glary COQ module by changing the maximum allowable temperature from  $T_c=110^\circ\text{C}$  to  $T_c=125^\circ\text{C}$  would unveil the “ostentatious” improvement of derating performance (curves). By operating a COQ48050N11M-10 module under conditions of  $T_a=95^\circ\text{C}$ ,  $T_c=110^\circ\text{C}$  and Airflow=200LFM with 90.9% of conversion efficiency, it

can deliver 5.0A output current with 2.50W power loss. If the allowable maximum temperature is  $T_c=125^\circ\text{C}$ , the allowable power loss will go to 4.76W and the available current could be 9.5A. Plot-1 shows comparison of derating curves for reference.



Plot-1: Derating curves for  $T_c=110^\circ\text{C}$  and  $T_c=125^\circ\text{C}$

However, even to increase the maximum allowable temperature from  $T_c=110^\circ\text{C}$  to  $T_c=125^\circ\text{C}$  would make dramatic improvement for derating performance, it in fact pays too much on operation life. Most of the circuit components used in modern power modules may reduce its life significantly due to operation under  $T_c=125^\circ\text{C}$  condition, and as a result the module life would be reduced by almost 50%. Generally, derating rule requests  $38^\circ\text{C}$  derating for power semiconductor junction temperature, and  $15^\circ\text{C}$  derating for  $T_g=130^\circ\text{C}$  rated PCB, that means the maximum operation temperature of the converter should be  $112^\circ\text{C}$ . All Glary industrial graded products' default OTP trigger point is set to be under  $110^\circ\text{C}$  for safe operation and longer converter life. Setting the case temperature of Glary module below  $90^\circ\text{C}$  during operation is highly recommended for securing the reliability of user's system.

## Module Thermal Resistance

Following the notes of module temperature section; the maximum allowable temperature for operation is

limited under  $T_c = 110^\circ\text{C}$ . Glary provide Sink-Plate technology for almost all Glary modules to reduce the module thermal resistance, and further improve thermal performance such as the derating performance and temperature deviation among the components. By choosing the Sink-Plate, the derating performance was improved dramatically and no any compromise is needed for the reliability and operation life because it can be used as an integrated heat sink to reduce the module thermal resistance when no additional cooling assembly is attached to the module.

In general, Glary modules are designed for board mount application, yet the Sink-Plate has at least 2pcs of M3 screws to allow the module to be attached to the casing, or to add an additional heat sink to extent its thermal performance to meet the requirements of high temperature operated system. The Sink-Plate is able to reduce the deflection that it has special geometry to hold flowed gap filler due mounting force during screw mounting process and improve the thermal contact to achieve unified temperature map and further improve the reliability.

The simple calculations for COQ with different types of base plate are described as below, which may be reflected to all Glary products and give better understanding about thermal performance and derating for specified application conditions:

#### **For the 1.0mm metal plate:**

The module thermal resistance  $\theta_M$  of COQ with 1.0mm metal plate is similar to traditional power module and can be listed as below:

$$\theta_M = 11.29 \text{ (Free-Air), } 7.36 \text{ (100LFM), } 5.65 \text{ (200LFM), } 4.20 \text{ (300LFM), } 3.47 \text{ (400LFM), } 3.03 \text{ (500LFM)}$$

The thermal resistance data and efficiency plot in the data sheet can be applied to the equation below to

determine the available power with specified operation ambient temperature.

$$P_o = (110 - T_a) / (\theta_M)(1/\eta - 1)$$

For example: 200LFM at  $T_a = 80^\circ\text{C}$  for COQ with 1.0mm metal plate. The available power is  $P_o = (110 - 80) / (5.65)(1/0.9 - 1) = 47.6\text{W}$ , or equal to 5.0V/9.5A output, which is also shown in the derating plots in the COQ data sheet.

#### **For the 3.0mm Sink-Plate:**

The module thermal resistance  $\theta_{S3}$  of COQ with 3.0mm Sink-Plate is about 30% lower compared to 1.0mm metal plate COQ module, which is listed as below:

$$\theta_{S3} = 9.13 \text{ (Free-Air), } 5.95 \text{ (100LFM), } 4.49 \text{ (200LFM), } 3.40 \text{ (300LFM), } 2.81 \text{ (400LFM), } 2.45 \text{ (500LFM)}$$

The thermal resistance data and efficiency plot in the data sheet can be applied to the equation below to determine the available power with specified operation ambient temperature.

$$P_o = (110 - T_a) / (\theta_{S3})(1/\eta - 1)$$

For example: 200LFM at  $T_a = 85^\circ\text{C}$  for COQ with 3.0mm metal plate. The available power is  $P_o = (110 - 85) / (4.49)(1/0.9 - 1) = 50.01\text{W}$ , or equal to 5.0V/10A output.

#### **For the 5.0mm Sink-Plate:**

The module thermal resistance  $\theta_{S5}$  of COQ with 5.0mm Sink-Plate is about 50% lower compared to 1.0mm metal plate COQ module were listed as below:

$$\theta_{S5} = 7.28 \text{ (Free-Air), } 4.91 \text{ (100LFM), } 3.17 \text{ (200LFM), } 2.44 \text{ (300LFM), } 2.01 \text{ (400LFM), } 1.83 \text{ (500LFM)}$$

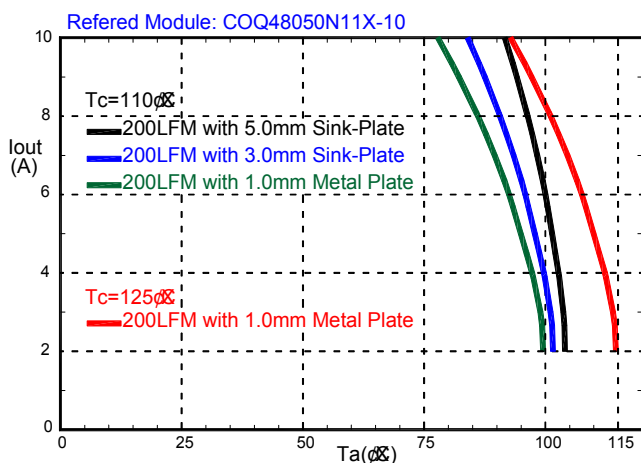
The thermal resistance data and efficiency plot in the data sheet can be applied to the equation below to determine the available power with specified operation ambient temperature.

$$P_o = (110 - T_a) / (\theta_{SS}) (1/\eta - 1)$$

For example: 200LFM at  $T_a = 92^\circ\text{C}$  for COQ with 5.0mm metal plate. The available power is  $P_o = (110 - 93)/(3.17)(1/0.9 - 1) = 48.26\text{W}$ , or equal to 5.0V/9.6A output.

### Comparison

Simple comparison of a COQ module with 1.0mm metal plat, 3.0mm Sink-Plate, 5.0mm Sink-Plate, and changing the OTP setting from  $T_c = 100^\circ\text{C}$  to  $T_c = 125^\circ\text{C}$  with a 1.0mm metal plate is shown as below Plot-2.



Plot-2: Comparison for  $T_c = 110^\circ\text{C}$  and  $T_c = 125^\circ\text{C}$

The result shows that the improvement on derating performance can be achieved to a very close result of  $T_c = 125^\circ\text{C}$  by using 5.0mm Sink-Plate with no increase on the maximum allowable temperature. The 3.0mm Sink-Plate also have significant improvement for high load condition. The Sink-Plate technology has no significant improvement for the light load condition, though, since it is already very close to the OTP point in that area.

### Conclusion

The high conversion efficiency characteristic is the basic requirement for the modern power module to achieve lowest power loss. However, the latest application is requesting for even more power in an even smaller package, which would naturally result in higher module temperature. This technical challenge is typically solved by raising the thermal limit, which "seems" to unveil the best effect to extract the available current, but paying much for converter's operation life is however left as an invisible price of exchange.

Moreover, it is very easy to neglect the fact that due to natural interaction between various tolerances of the components used in a power converter, de-rating performance of different units of the same model can be similar but not exactly the same. A higher OTP set point may also result in de-rating curves that "appear" to be much better. However, the key consideration should always be whether or not the other devices in the user's system are able to survive in a constant high temperature environment. The de-rating curves, calculated or actual measured, are therefore used as a reference only and it is strongly recommended for the actual usage to run the units under the curves' limits in real application.

What Glary Power has to offer as a viable and relatively more reliable alternative solution, is to reduce the module thermal resistance by applying various base plate types or even full metal packages to further eliminate the hot spots. Such solutions actually request for a low profile converter design to have all the components on one single side of the converter PCB especially when parts count dominates as such a critical factor of the converter life that simply increasing the maximum allowable operating temperature would naturally and directly influence the parts lives. Eventually as a result, Glary Power's

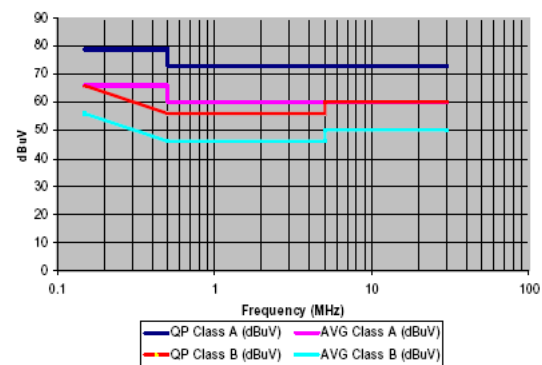
solution is able to cool down the module and further make it more viable to deliver more power with no impact on the reliability and safe operation life.

## Module Noise Considerations

### Input Side Conducted Noise

#### Conductive EMC Regulations

In order to achieve an useful EMC filter circuit design, the limits of conducted emissions EN55011/FCC derived from CISPR22 was shown as below and it must be well understood.



The class A and class B requirements referring to the industrial standard and the domestic standard depend on the antenna used for detecting the noise. The European standards give a higher limit for quasi-peak antenna and the lower limit for average antenna, and both limits must be met for the equipment to pass. The FCC standards used in North America have similar specifications.

#### Common Mode Noise

Common mode noise is one major noise source of a power module. It comes from a common-mode current caused by fast voltage change on the switching device and coupled through capacitances between the switching device and other components. The common-mode energy travels on all the lines or wires in the same direction at the same time, and further cause all the devices between the lines to perform no attenuation. However, a common mode choke or a ground choke may provide impedance between the lines and ground to reduce common current. To



connect capacitors between the lines and ground properly would also be helpful to reduce the noise.

### Differential Mode Noise

Differential-mode noise is the AC-component of pulsating input current that is caused by pulsating switching current in power stage of power module. This produces a noise voltage between the positive and negative input power terminal, which is opposite in direction or phase with respect to each other. Generally, all Glary converters have an internal input filter circuit to filter the differential-mode conducted noise. However, an external capacitor should be placed between input lines to further reduce the noise level to meet EMC requirement. The capacitor should be placed close to the module to minimize the loop cross-sectional area and further reduce possible emission due to high frequency ripple current. To twist the input leads or layout a PCB power planes would also be helpful for noise cancellation and to eliminate second order coupling from the near-field magnetic flux radiation.

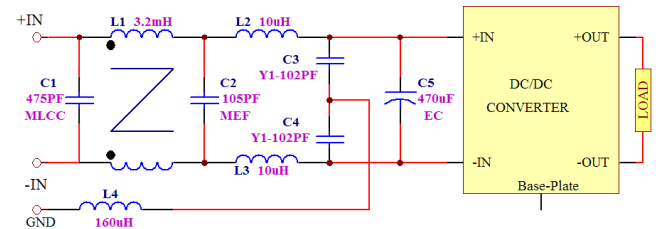
### Bandwidth of EMC Components

No component is ideal for all frequency ranges. Capacitor may lose its capacitive property when the lead inductance dominates its impedance and inductor will become a capacitive element when parasitic capacitance becomes important at high frequency. The Bandwidth of EMC Components should be taken into consideration when designing an EMC filter circuit. To connect ceramic capacitor(s) with electricity capacitor in parallel and connect low inductance inductor(s) of reasonably large size should unveil a better bandwidth.

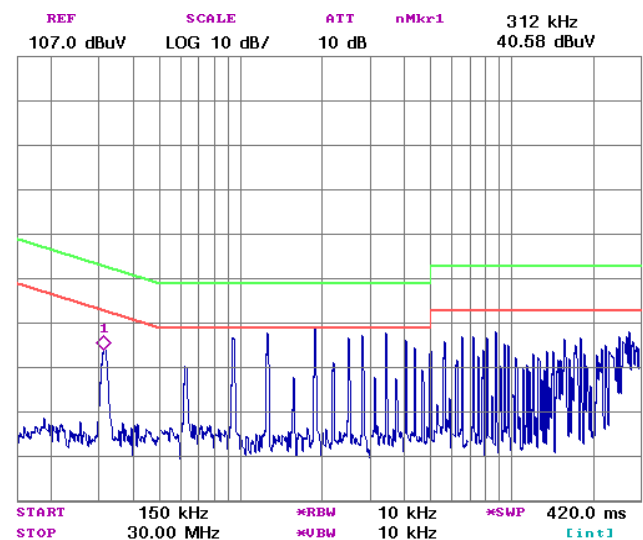
### Referenced EMC Circuit

The referenced EMC circuit was made by verifying a 600W UH48120P20M-S50 power module that is shown here for a reference to design an useful EMC

filter for the user's system. It should be noted that the circuit values might need to be modified to meet different requirements in various applications.



The tested curve is shown as below to demonstrate the performance of the referenced EMC filter circuit with for UH48120P20M-S50 module.



### Radiated Noise

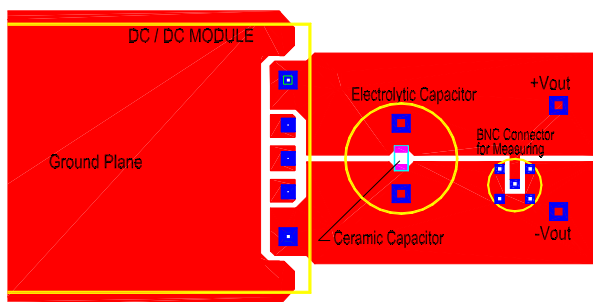
The magnetic field radiation and electric field radiation were called “near-field” radiation that decays quickly as a function of distance not usually affects the radiated measurements. However, electromagnetic radiation caused by high frequency current flow through circuit element or traces can be radiated to far distance, it can be minimized by proper board layout that keeps all leads with AC current short circuit; To twist or run those leads as ground planes to minimize loop cross-sectional area would also be greatly helpful. Glary has six-side metal package option for



several product series and could provide extra RFI shielding performance for critical application. It should be noted that in many cases if the device fails in the common mode current test, it will also fail in the radiated-emission test since the lines would carry common mode noise and perform as an antenna to emit radiated noise.

## Output Side Ripple/Noise

The output ripple/noise performance can be improved by adding more low-ESR external capacitors closed to output terminals. The reference trace layout that should provide corrective measuring capability and improve output ripple/noise performance is shown as below.



Note that the result of noise measurement on the bench can be worse than the actual performance with the system when *the bench measurement ignores one little fact --- Improper test set up might form up the shape of an unwanted antenna that significantly confuses the test result.* On the bench, some engineers would use probes (instead of BNC connectors) to hitch the converter's pins, and read the result. That way, the probes would form up the shape of an antenna, which would bypass the internal filter circuit of the converter and pick up radiation noise that is supposed to be filtered inside the converter already. Such incorrect measurement would read big noise readings and will never pass.

Therefore, the MLCC in the above reference layout is

apparently needed to filter the noise outside of the converter, and capture the true reading of the ripple.

Note that it is no use to put that MLCC inside the converter, because as said, the extra noise is because the "antenna" bypasses the internal filter. That being said, even by adding that MLCC to the converter's internal filter circuit, it would still be bypassed. Without adding a MLCC outside and nearby the output side, the probes would always read much higher and incorrect noise and create illusion to the tester that it does not pass ripple.

## General Application Information

### Storage/Handling

#### Module Storage

It is user's liability to avoid module being overexposure to moisture during storage; board mount assembly and board rework. A below 30°C temperature and 85%RH storage condition is acceptable for max.24 hours on line storage to avoid possible risk from wave soldering process.

The solder terminal plating material of Glary module is gold metal, which can meet MSL1 level requirement for long-term storage. However, the module must go through a de-moisture process by being placed into a chamber of 85°C for 12 hours before use, to prevent the module from risk of explosion caused by heated moisture during soldering process. The recommended module storage condition is 30°C-60%RH.

#### Module Handling

The user must take responsibility during storage, board mount assembly and board rework to avoid module over stress due to drop, impact or any kind of tools touch to its surface and components. The user should also prevent the module from the damage of electrostatic discharge. Except for activities following the application notes herein stated, any extra direct work without consulting and/or consensus with Glary, including but not limit to cutting pins, adding or removing potting compound or glues or enclosures, unauthorized electrical and/or mechanical analysis, would result in waiver of Glary's service and warranty liabilities whatsoever.

### Soldering

#### Hand Soldering

Hand soldering is the preferred method for Glary module due to the variability of the amount of solder applied, the time the soldering iron is held on the joint,

the temperature of the iron, and the temperature of the solder joint. A temperature-controlled 70W solder iron with 0.125" tip and 425°C setting is suitable for terminal soldering work. The soldering time is 3S~6S for 0.04" terminal pin diameter, 5S~10S for 0.06" terminal pin diameter and 8S~16S for 0.08" terminal pin diameter.

The above guidelines may require modification to optimize the soldering time for user's particular circuit board or soldering iron. The exact soldering time and temperature for user's specific application can be determined by mounting a thermocouple to the power module terminal using high-temperature solder. The minimum soldering time is defined as the time required for the terminal to reach 125°C. The maximum soldering time is the time required for the terminal to reach 165°C. The power module's internal temperature must stay below the storage temperature of 183°C or at least less than the critical continuous temperature of 183°C.

#### Wave Soldering

Glary understands that wave soldering is the most popular soldering method for the solder attachment of through-hole component leads for mass volume productions. Glary power modules are designed to be compatible with single-wave, dual-wave or turbid-wave soldering machines. The suggested soldering process is to keep the power module's internal temperature below 183°C. The typical recommended preheat temperature range is between 90°C and 105°C on the module-side of the circuit board. The pin-side of circuit board preheat temperature is recommended to be greater than 120°C, and preferable within 100°C of the solder-wave temperature, a maximum preheat rate of 4°C/s of the solder-wave temperature, a maximum preheat rate of 4°C/s is suggested. The maximum recommended solder pot temperature is 250°C with a typical solder-

wave dwell time of 3 seconds or up to 6 seconds maximum.

### To remove a module soldered on board

Note that the correct way to remove a part soldered on the system board is to desolder it instead of any other way. The tool in the following link can be a good example and reference for desoldering a module:

[https://www.hakko.com/english/products/hakko\\_fm204.html](https://www.hakko.com/english/products/hakko_fm204.html)

All one needs to do is to stick the desoldering head on top of the back of each pin's solder point, and it would heat up the point very quickly with minimized risk of hurting the system board, and further remove the converter easily. See below link that further demonstrates how it works:

[https://www.youtube.com/watch?v=yNW\\_7YUYtS8](https://www.youtube.com/watch?v=yNW_7YUYtS8)

## Cleaning/Drying

### Cleaning

Post solder cleaning is usually the final process of circuit board assembly prior to electrical-board testing. The result of inadequate circuit board cleaning can affect both the reliability of a power module and the testability of the finished circuit-board assembly. Glary power modules are compatible with most cleaning processes but the cleaning materials should be chosen to be compatible with plastic parts or potted silicone material inside the module. Incompatible cleaning material may cause malfunction or reduce its long-term operation reliability.

### Drying

The drying process should be equipped with blowers capable of generating 1000CFM of air or above, so that the amount of rinse water left can be dried off with least heat. Hand held air guns are not

recommended due to the variability and non-consistency of the operation. For open-frame power module constructions with magnetic structures (transformers and inductors) that have un-potted windings or cavities, a heating process of 100°C-0.5 hours inside the chamber is recommended for the assembly to ensure that the moisture and other potential foreign contaminants are driven out from the open windings and cavities and further ensure that no residues would affect long-term reliability and isolation voltage.

## Pad Layout

The pad layout of Glary power module depends on its current rating. The low current model just requires a simple through hole to carry load current. However, the large current models would introduce high  $I^2R$  loss at the solder point, which may cause over heating effect and further reduce the reliability. The pad layout for high current terminal pins becomes the most important consideration of the circuit board design.

### Through Hole Size

#### **For the 0.04" (1.0mm) terminal pins:**

Use the 0.05" (1.25mm) diameter plated through hole with minimum 0.08" (2.0mm) diameter solder pad for all modules layout.

#### **For the 0.06" (1.5mm) terminal pins:**

Use the 0.075" (1.80mm) diameter plated through hole with minimum 0.12" (3.0mm) diameter solder pad for the low current circuit board layout. Based on the layout described above, it is necessary to have 4pcs~8pcs 0.5mm diameter of current distribution via to surround each through hole for reducing the current density and  $I^2R$  loss while the current is high. The optional double pin layout will be necessary when ultra high current module was used.

#### **For the 0.08" (2.0mm) terminal pins:**

Low Current Module: use the 0.10" (2.54mm)

diameter plated through hole with minimum 0.16" (4.0mm) diameter solder pad for the circuit board layout.

High Current Module: use the 0.10" (2.54mm) diameter plated through hole with minimum 0.16" (4.0mm) diameter solder pad for the circuit board

layout. It is necessary to have 5pcs~10pcs 0.5mm diameter of current distribution via to surround each through hole to reduce the current density and  $I^2R$  loss. The optional double pin layout will be necessary when ultra high current module was used.